



## FQP10N60C/FQPF10N60C

### 600V N-Channel MOSFET

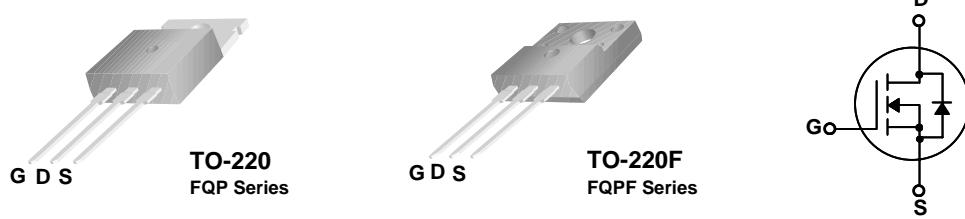
#### General Description

These N-Channel enhancement mode power field effect transistors are produced using Corise Semiconductor's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply.

#### Features

- 9.5A, 600V,  $R_{DS(on)} = 0.73\Omega$  @  $V_{GS} = 10$  V
- Low gate charge ( typical 44 nC)
- Low  $C_{rss}$  ( typical 18 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



#### Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

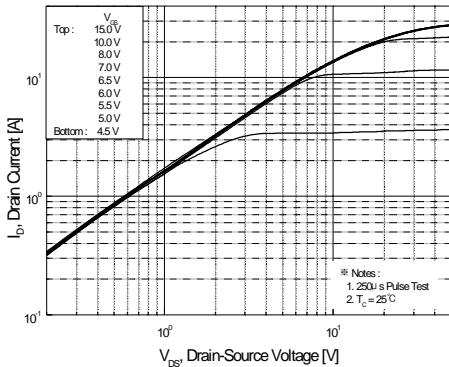
Symbol	Parameter	FQP10N60C	FQPF10N60C	Units
$V_{DSS}$	Drain-Source Voltage	600		V
$I_D$	- Continuous ( $T_C = 25^\circ\text{C}$ )	9.5	9.5 *	A
	- Continuous ( $T_C = 100^\circ\text{C}$ )	3.3	3.3 *	A
$I_{DM}$	Drain Current - Pulsed	(Note 1)	38	A
$V_{GSS}$	Gate-Source Voltage		$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	700	mJ
$I_{AR}$	Avalanche Current	(Note 1)	9.5	A
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	15.6	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	4.5	V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	156	50	W
	- Derate above $25^\circ\text{C}$	1.25	0.4	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	$^\circ\text{C}$

\* Drain current limited by maximum junction temperature.

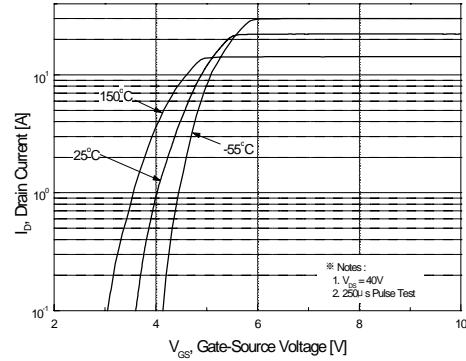
#### Thermal Characteristics

Symbol	Parameter	FQP10N60C	FQPF10N60C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.8	2.5	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^\circ\text{C}/\text{W}$

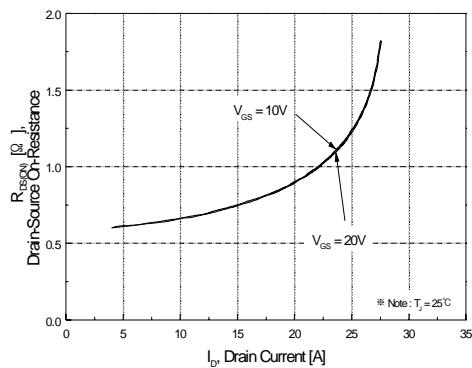




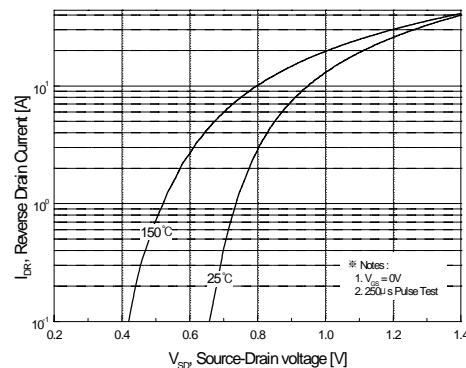
**Figure 1. On-Region Characteristics**



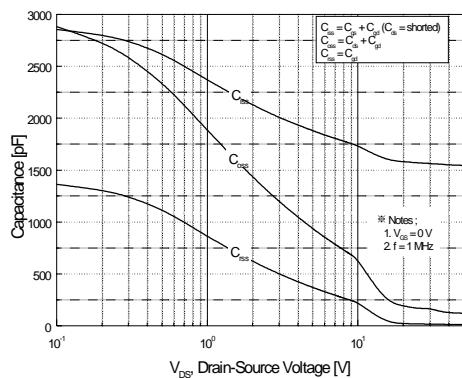
**Figure 2. Transfer Characteristics**



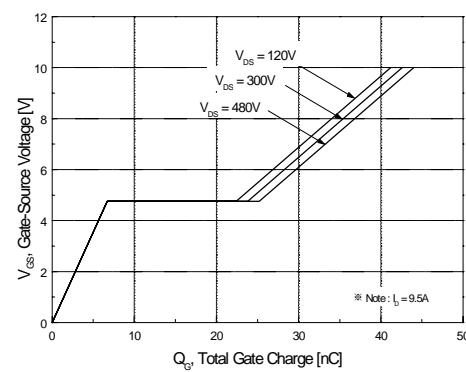
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



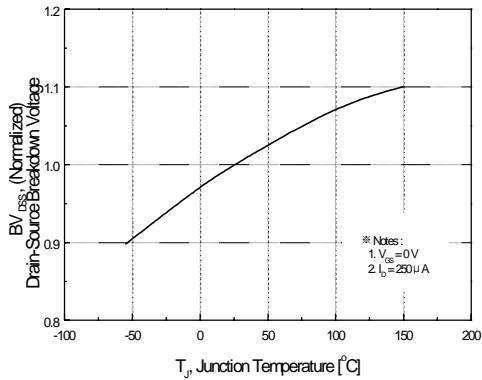
**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**



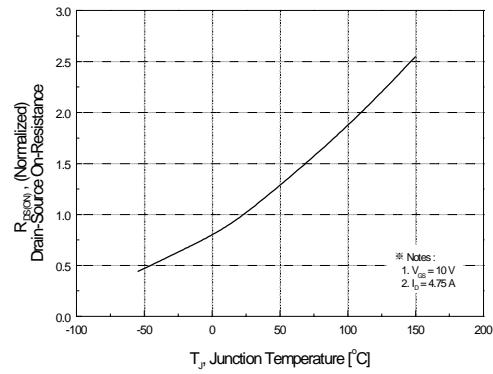
**Figure 5. Capacitance Characteristics**



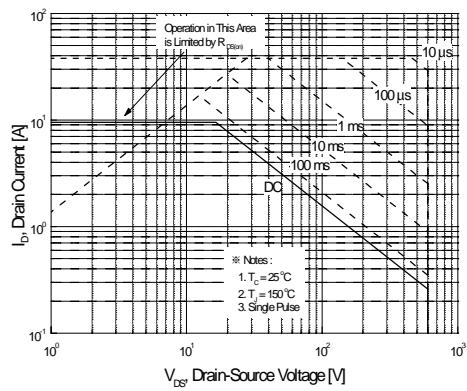
**Figure 6. Gate Charge Characteristics**



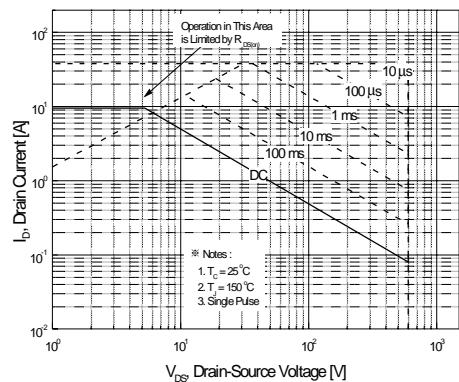
**Figure 7. Breakdown Voltage Variation vs Temperature**



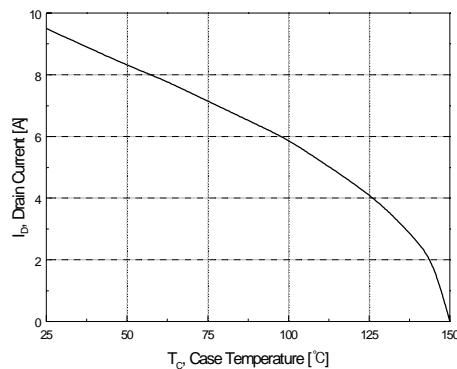
**Figure 8. On-Resistance Variation vs Temperature**



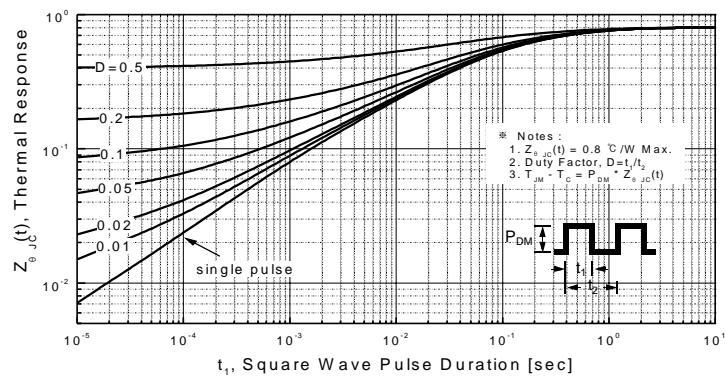
**Figure 9-1. Maximum Safe Operating Area for FQP10N60C**



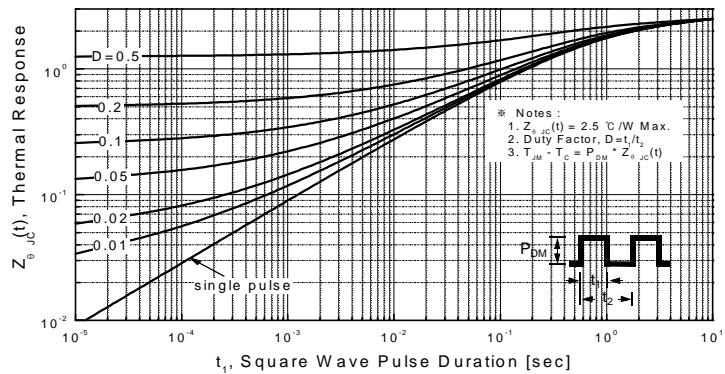
**Figure 9-2. Maximum Safe Operating Area for FQPF10N60C**



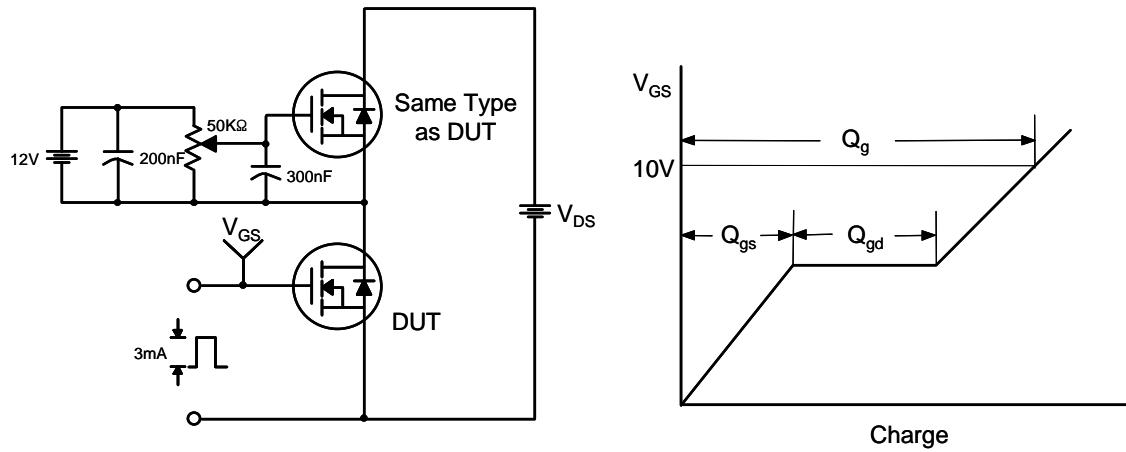
**Figure 10. Maximum Drain Current vs Case Temperature**



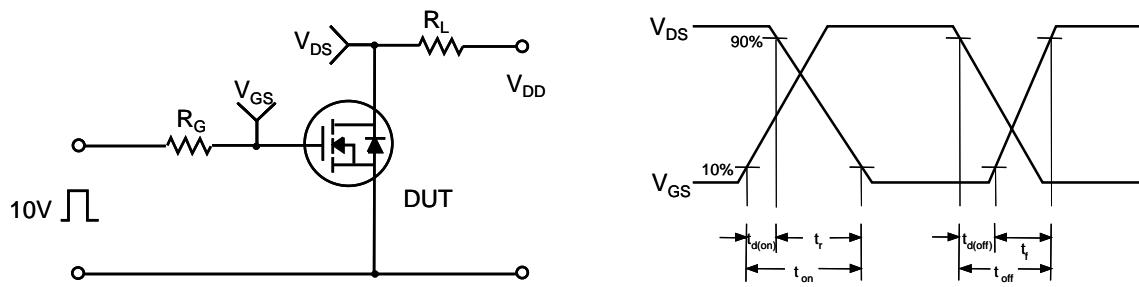
**Figure 11-1. Transient Thermal Response Curve for FQP10N60C**



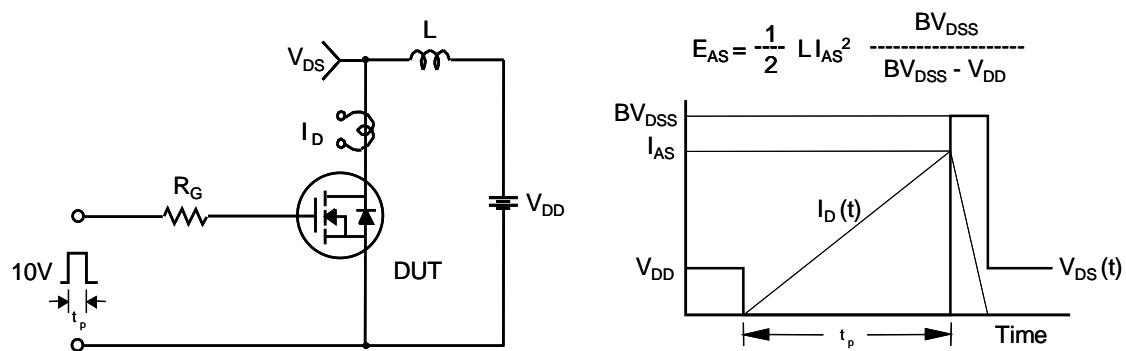
**Figure 11-2. Transient Thermal Response Curve for FQPF10N60C**

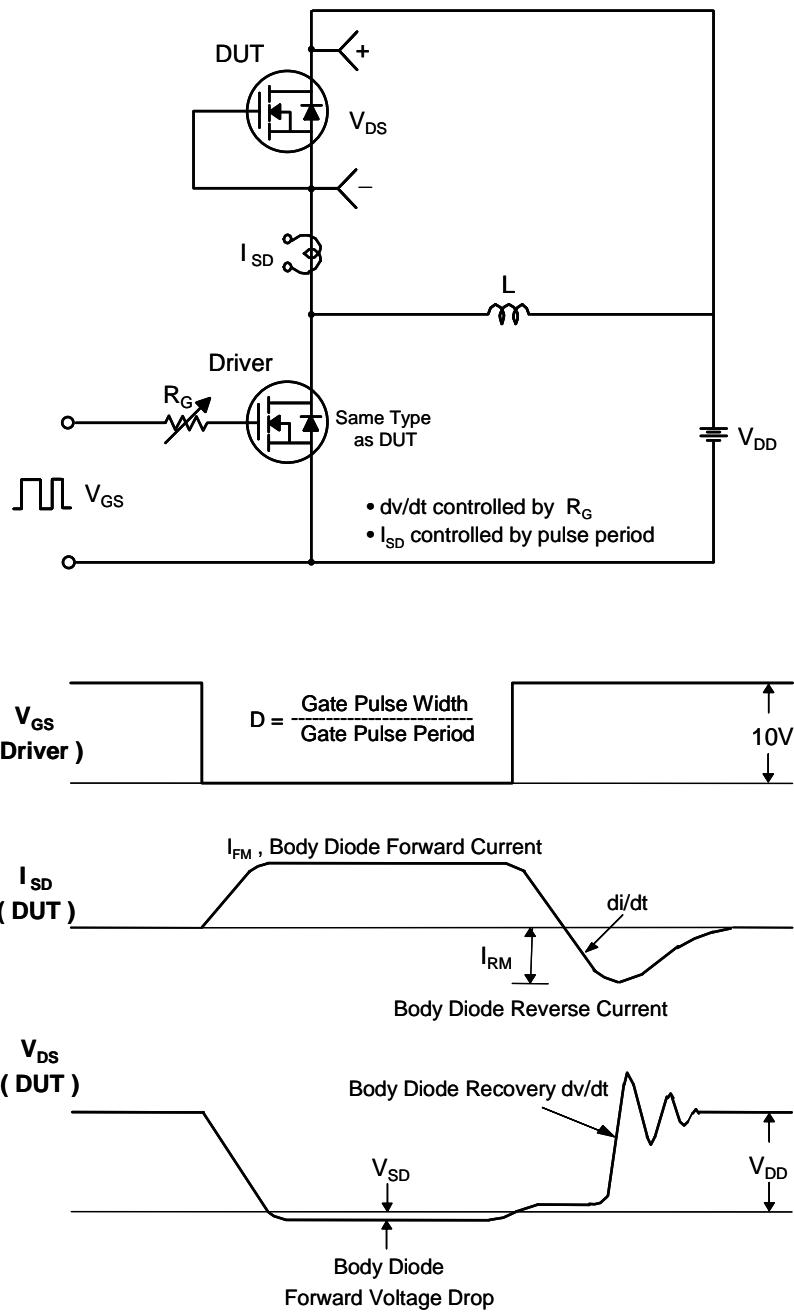


Resistive Switching Test Circuit & Waveforms



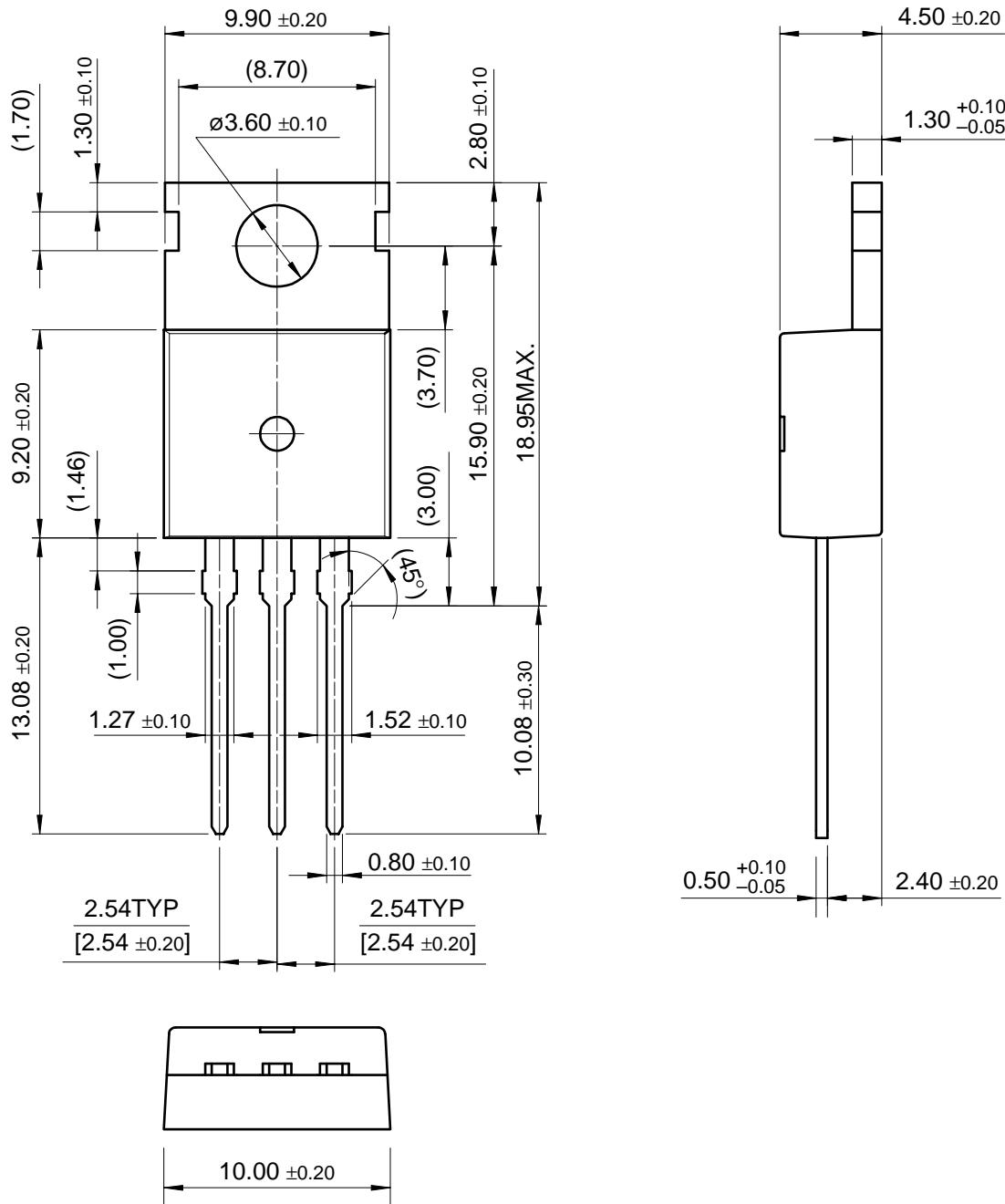
Unclamped Inductive Switching Test Circuit & Waveforms





**FQPF10N60C/FQPF10N60C**

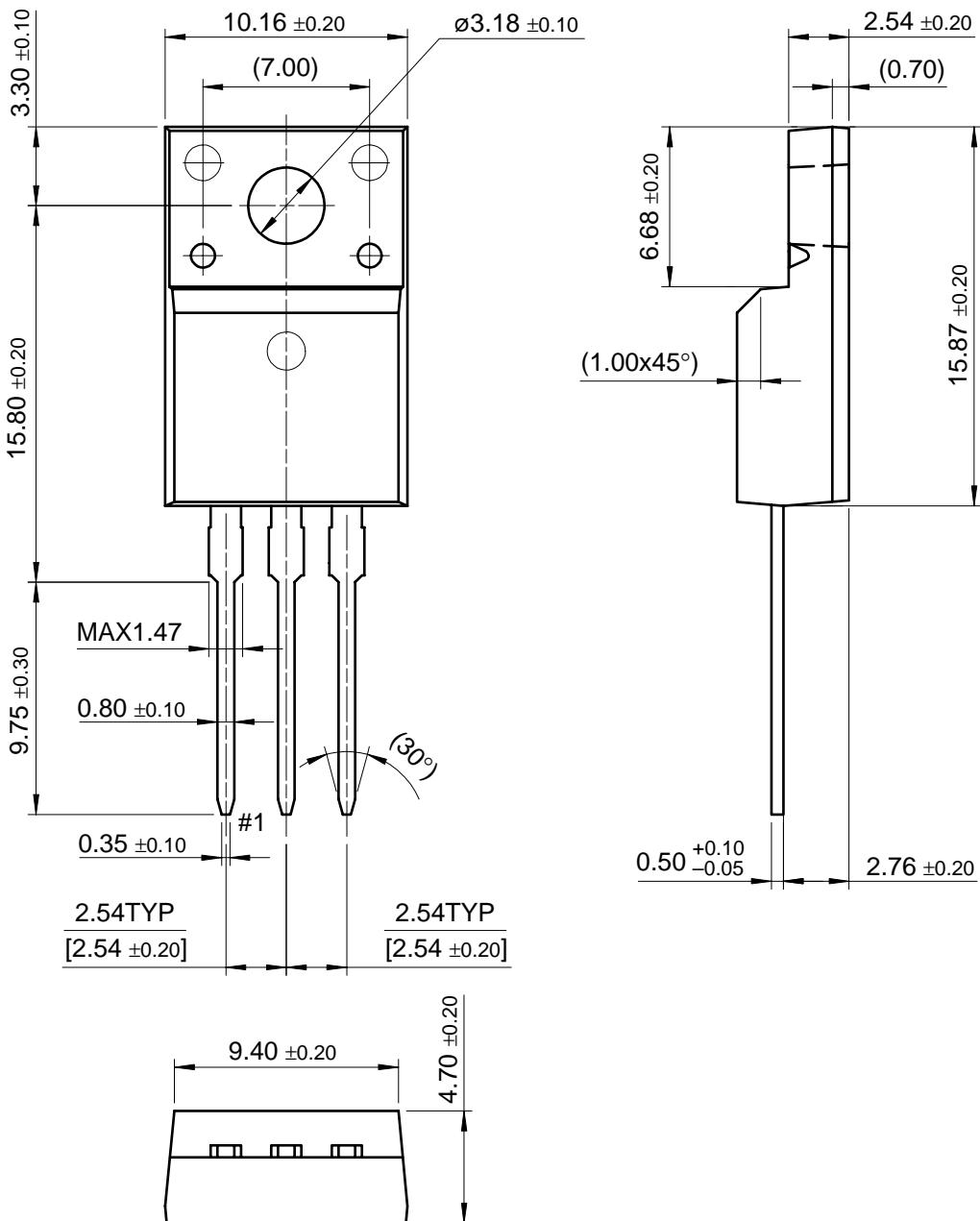
**TO-220**



Dimensions in Millimeters

**FQP10N60C/FQPF10N60C**

**TO-220F**



Dimensions in Millimeters